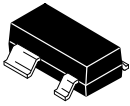


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DISCONTINUE

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CALE 4:1

SOT-143

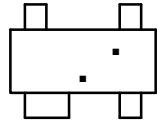
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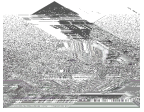
DIM	MILLIME E	
	MIN	MA
A	0.80	1.12

	0.30	0.51
1	0.76	0.94
	0.08	0.20
D	2.80	3.05

E1	1.20	1.40
e	1.92 BSC	
L	0.35	0.70

GENERIC MARKING DIAGRAM*

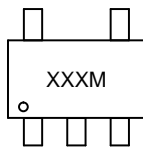




SOT 23, 5 Lead
CASE 527AH
ISSUE A

DATE 09 JUN 2021

**GENERIC
MARKING DIAGRAM***

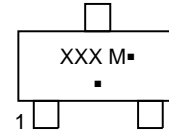
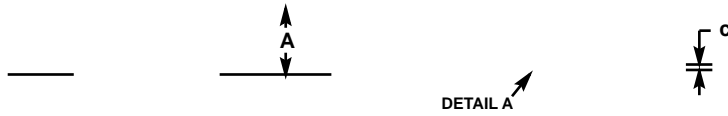
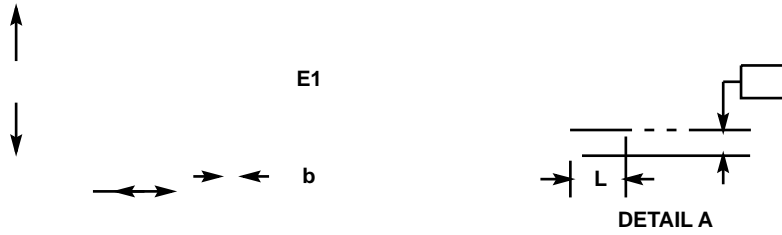


XXX = Specific Device Code
M = Date Code

*This information is generic. Please refer to

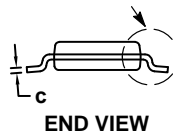
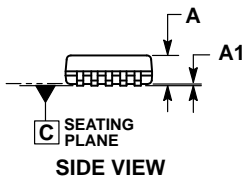
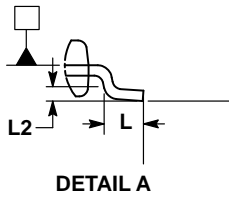
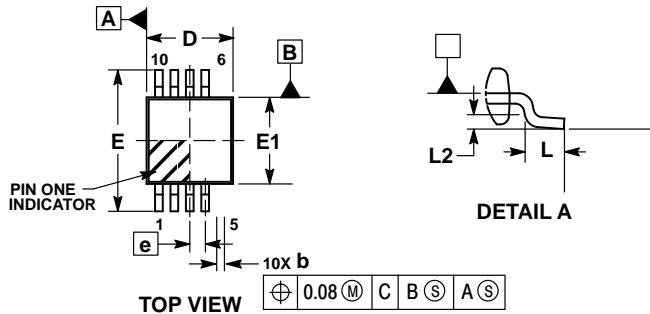
SOT-23, 6 Lead
CASE 527AJ

SCALE 2:1

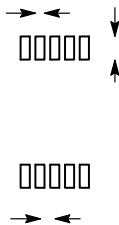


- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "



**RECOMMENDED
SOLDERING FOOTPRINT***

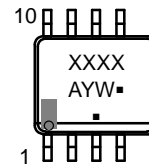


- NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSIONS: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN EXCESS OF MAXIMUM MATERIAL CONDITION.
 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. DIMENSION E DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
 5. DATUMS A AND B TO BE DETERMINED AT DATUM F.
 6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

DIM	MILLIMETERS	
	MIN	NOM
A	---	---
A1	0.00	0.05

b	0.17	---
c	0.13	---
D	2.90	3.00
E	4.75	4.90
E1	2.90	3.00
e	0.50 BSC	
L	0.40	0.70
L1	0.95 REF	
L2	0.25 BSC	

**GENERIC
MARKING DIAGRAM***



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present and may be in either location. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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